

Amendments to the Specification:

Please replace the paragraph bridging pages 29 and 30 with the following amended paragraph:

When an ID chip is attached to an object having a curved surface, which is created by a ~~bus-bar~~ generatrix on a conical surface, a cylindrical surface or the like, and the second substrate 548 of the ID chip is also curved, it is preferable that the direction of the ~~bus-bar~~ generatrix is the same as a movement direction of carriers of the TFTs 529 to 531. According to the structure, adverse affects due to bending of the second substrate 548 to the characteristics of the TFTs 529 to 531 can be prevented. The percentage of area in the integrated circuit occupied by the island-like semiconductor film is set 1 to 30%, thereby suppressing adverse affects to the characteristics of the TFTs 529 to 531 even when the second substrate 548 is bent.